

**Search Notes**

**Application/Control No.**

10/693,896

**Examiner**

Stephen W. Smoot

**Applicant(s)/Patent under Reexamination**

CHEN ET AL.

**Art Unit**

2813

**SEARCHED**

Class	Subclass	Date	Examiner
438	108	1/27/2005	SWS
438	612	1/27/2005	SWS
438	613	1/27/2005	SWS
438	614	1/27/2005	SWS
257	738	1/27/2005	SWS
257	E21.508	1/27/2005	SWS
29	842	1/27/2005	SWS
Updated	Above	5/9/2005	SWS
438	615	5/9/2005	SWS
228	180.22	5/9/2005	SWS

**INTERFERENCE SEARCHED**

Class	Subclass	Date	Examiner
Same as Above	5/9/2005	SWS	<i>S.W.S.</i>

**SEARCH NOTES  
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Key Words: Solder Ball, Bump - Flux; Active Surface; Bond Pad; Under Bump Metallurgy;	1/27/2005	<i>S.W.S.</i> SWS
Passivation Layer; Solder Reflow; Solid Flux.	1/27/2005	<i>S.W.S.</i> SWS
Updated Above Search	5/9/2005	<i>S.W.S.</i> SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	1/27/2005	<i>5-9-05 S.W.S.</i> SWS